

PART INFORMATION		
Mfg Item Number	MMA8225KEG	
Mfg Item Name	SENSOR 16SOICW ACCEL	
SUPPLIER		
Company Name	Freescale Semiconductor Inc	
Company Unique ID	14-141-7928	
Response Date	2017-05-01	
Response Document ID	0226A1.20	
Contact Name	Freescale Semiconductor Inc	
Contact Title	Product Technical Support	
Contact Phone	1-800-521-6274	
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Authorized Representative	Daniel Binyon	
Representative Title	EPP Customer Response	
Representative Phone	512-895-3406	
Representative Email	eppanlst@freescale.com	
URL for Additional Information	www.freescale.com	
DECLARATION		
EU RoHS	Yes	
Pb Free	No	
HalogenFree	No	
Plating Indicator	e3	
EU RoHS Exemption(s)	7c-I	
MANUFACTURING		
Mfg Item Number	MMA8225KEG	
Mfg Item Name	SENSOR 16SOICW ACCEL	
Version	ALL	
Weight	0.609200	
UoM	g	
Unit Volume	EACH	
J-STD-020 MSL Rating	3	
Peak Processing Temperature	250 C	
Max Time at Peak Temperature	30 seconds	
Number of Processing Cycles	3	

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.
RoHS Declaration	4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemption List Version	2012/51/EU
Exemptions in this part	7c-I:Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
List of Freescale Accepted Exemptions	6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight 6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight 6(c) : Copper alloy containing up to 4% lead by weight 7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead) 7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications 7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound 7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher 7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC 7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors 15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages

MATERIAL COMPOSITION

Homogeneous Material	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%		ARTICLEPPM	ARTICLE%
Epoxy Die Attach	0.0013						g					
Epoxy Die Attach		Cadmium/Cadmium Compounds	Cadmium	7440-43-9		0	g	3	0.0003		0	0
Epoxy Die Attach		Plastics/polymers	Phenolic Polymer Resin, Epikote 155	9003-36-5		0.00017906	g	137740	13.774		293	0.0293
Epoxy Die Attach		Lead/Lead Compounds	Lead	7439-92-1		0.00000001	g	7	0.0007		0	0
Epoxy Die Attach		Plastics/polymers	Phenol, polymer with formaldehyde	9003-35-4		0.00003939	g	30303	3.0303		64	0.0064
Epoxy Die Attach		Metals	Silver, metal	7440-22-4		0.00108154	g	831947	83.1947		1775	0.1775
Non-Conductive Epoxy/Adhesive	0.0048						g					
Non-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Silicone gum	67762-04-1		0.00004956	g	10324	1.0324		81	0.0081
Non-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Siloxanes and Silicones, di-Me, Me vinyl, vinyl group-terminated	68083-18-1		0.00058997	g	122911	12.2911		968	0.0968
Non-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Siloxanes and silicones, di-Me, vinyl group-terminated	68083-19-2		0.00198799	g	393313	39.3313		3098	0.3098
Non-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Proprietary Material-Other siloxanes and silicones	-		0.00106195	g	221239	22.1239		1743	0.1743
Non-Conductive Epoxy/Adhesive		Glass	D4 and HMDZ treated Silicon Dioxide	68937-51-9		0.00070797	g	147493	14.7493		1182	0.1182
Non-Conductive Epoxy/Adhesive		Glass	Silica, crystalline - quartz (SiO2)	14808-60-7		0.00044838	g	93412	9.3412		736	0.0736
Non-Conductive Epoxy/Adhesive		Metals	Titanium (IV) Oxide	13463-67-7		0.00005428	g	11308	1.1308		89	0.0089
Lead Frame Plating	0.0077						g					
Lead Frame Plating		Lead/Lead Compounds	Lead	7439-92-1		0.00000154	g	209	0.02		2	0.0002
Lead Frame Plating		Metals	Tin, metal	7440-31-5		0.00769846	g	998000	99.98		12636	1.2636
Copper Lead Frame	0.1579						g					
Copper Lead Frame		Metals	Copper, metal	7440-50-8		0.1520849	g	963955	96.3955		249849	24.9849
Copper Lead Frame		Solvents, additives, and other materials	Phosphorus, elemental (not containing red allotrope)	7723-14-0		0.00013027	g	825	0.0825		213	0.0213
Copper Lead Frame		Metals	Iron, metal	7439-89-6		0.00371065	g	23500	2.35		6091	0.6091
Copper Lead Frame		Lead/Lead Compounds	Lead	7439-92-1		0.00002694	g	170	0.017		44	0.0044
Copper Lead Frame		Metals	Silver, metal	7440-22-4		0.001579	g	10000	1		2591	0.2591
Copper Lead Frame		Metals	Tin, metal	7440-31-5		0.00004737	g	305	0.03		77	0.0077
Copper Lead Frame		Metals	Zinc, metal	7440-66-6		0.00019738	g	1250	0.125		323	0.0323
Die Encapsulant	0.4113						g					
Die Encapsulant		Metals	Aluminum, metal	7429-90-5		0.00020524	g	499	0.0499		336	0.0336
Die Encapsulant		Antimony/Antimony Compounds	Antimony trioxide	1309-64-4		0.01232543	g	29967	2.9967		20232	2.0232
Die Encapsulant		Bismuth/Bismuth Compounds	Bismuth	7440-69-9		0.00102702	g	2497	0.2497		1685	0.1685
Die Encapsulant		Flame Retardants	Bromophenol, formaldehyde, epichlorohydrin polymer	68541-56-0		0.00821695	g	19978	1.9978		13488	1.3488
Die Encapsulant		Solvents, additives, and other materials	Other halogenated organic compounds	-		0.00821695	g	19978	1.9978		13488	1.3488
Die Encapsulant		Solvents, additives, and other materials	Carbon Black	1333-86-4		0.00123267	g	2997	0.2997		2023	0.2023
Die Encapsulant		Metals	Magnesium, metal	7439-95-4		0.00020524	g	499	0.0499		336	0.0336
Die Encapsulant		Solvents, additives, and other materials	Other organic phosphorous compounds	-		0.00123267	g	2997	0.2997		2023	0.2023
Die Encapsulant		Solvents, additives, and other materials	Other organic Silicon Compounds	-		0.00287581	g	6992	0.6992		4720	0.472
Die Encapsulant		Plastics/polymers	Phenol, polymer with formaldehyde	9003-35-4		0.02054238	g	49945	4.9945		33720	3.372
Die Encapsulant		Plastics/polymers	Other polymers	-		0.03697669	g	89902	8.9902		60697	6.0697
Die Encapsulant		Glass	Silica, vitreous	60676-86-0		0.31824295	g	773749	77.3749		522416	52.2416
Bonding Wire	0.0017						g					
Bonding Wire		Metals	Gold, metal	7440-57-5		0.0017	g	1000000	100		2790	0.279
Bonding Wire	0.0017						g					
Bonding Wire		Metals	Gold, metal	7440-57-5		0.0017	g	1000000	100		2790	0.279
Die Overcoat	0.0055						g					
Die Overcoat		Solvents, additives, and other materials	Ethylbenzene	100-41-4		0.00006513	g	11842	1.1842		106	0.0106
Die Overcoat		Glass	Silylated silica	68909-20-6		0.001375	g	250000	25		2257	0.2257
Die Overcoat		Plastics/polymers	Poly(dimethylsiloxane)A, hydroxy terminated	70131-67-9		0.00405987	g	738158	73.8158		6664	0.6664
Pb Glass Frit Semiconductor Di	0.0088				7c-I		g					
Pb Glass Frit Semiconductor Di		Lead/Lead Compounds	Lead (II) titanate	12060-00-3		0.00009135	g	10381	1.0381		149	0.0149
Pb Glass Frit Semiconductor Di		Glass	Fibrous-glass-wool	65997-17-3		0.0000875	g	9943	0.9943		143	0.0143
Pb Glass Frit Semiconductor Di		Solvents, additives, and other materials	2,2,4-trimethyl-1,3-pentanediol-1-monooisobutyrate	25265-77-4		0.0000875	g	9943	0.9943		143	0.0143
Pb Glass Frit Semiconductor Di		Glass	Silicon, doped	-		0.00853365	g	969733	96.9733		14007	1.4007
Silicon Semiconductor Die	0.0085						g					
Silicon Semiconductor Die		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%)	-		0.00017	g	20000	2		279	0.0279
Silicon Semiconductor Die		Glass	Silicon, doped	-		0.00833	g	980000	98		13673	1.3673

LINKS	
MCD LINK	
NXP website	http://www.nxp.com
GENERAL ENVIRONMENTAL COMPLIANCE LINKS	
RoHS signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ROHS-DECLARATION.pdf
China RoHS	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/china-rohs:ENV_CHINA_ROHS_STRATEGY
REACH signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-REACH-STATEMENT.pdf
ELV signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ELV-STATEMENT.pdf
Conflict Minerals statement	http://www.nxp.com/files/corporate/doc/support_info/NXP-STATEMENT-CONFLICT-MINERALS.pdf
NXP ENVIRONMENTAL INFORMATION	
Environmental Compliance website	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization:ABUENVPRFPRDX
FAQ	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/eco-product-faqs:ENVIRON_FAQ
Technical Service Request	http://www.nxp.com/support/sales-and-support:SUPPORTHOME
LINKS TO BLANK IPC1752 FORMS	
Blank IPC1752 v1.1 Form	http://www.NXP.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf

IPC1752 XML LINKS

http://www.freescale.com/mcds/MMA8225KEG_IPC1752_v11.xml

http://www.freescale.com/mcds/MMA8225KEG_IPC1752A.xml